AMENDMENTS TO CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A processor loading apparatus comprising:

a board member;

a processor socket mounted on the board member;

a processor seated in the processor socket;

a frame member comprising a heat sink engagement surface and mounted on the board member;

a plurality of connector portions on the frame member;

a curved resilient load member comprising a load member surface, wherein the curved resilient load member comprises ~~with~~ a first end connected to one of the connector portions and a second end connected to another one of the connector portions, whereby the connection of the second end deforms the curved load member into a substantially parallel engagement with the processor ~~and~~ such that the load member surface is located below the heat sink engagement surface and the curved resilient load member applies a constant compressive force to the processor sufficient to mate the processor with the processor socket; and

the resilient load member having an opening formed therein permitting the processor to extend through the opening into contact with a heat sink, whereby the deformation of the curved resilient load member into a substantially parallel engagement with the processor results in a ~~secondary~~ non-compressive force that is ~~capable of warping the processor and results from the resilient load member applying the constant compressive force is~~ not transferred to the processor socket due to the coupling of the curved resilient load member to the frame member.

2. (Original) The apparatus of claim 1 wherein the frame member surrounds the processor socket.

3. (Original) The apparatus of claim 1 further comprising:

a support member mounted on the board member adjacent to the frame member.

4. (Original) The apparatus of claim 1 wherein the first end of the resilient load member is pivotally connected to one of the connector portions and the second end is latched to another one of the connector portions.

5. (Original) The apparatus of claim 1 wherein the processor includes a thermal connection surface.

6. (Canceled)

7. (Currently Amended) A heat sink mounting apparatus comprising:

a board member;

a support member mounted on the board member;

a processor socket mounted on the board member;

a processor seated in the processor socket;

a frame member comprising a heat sink engagement surface and mounted on the board member;

a plurality of connector members on the frame member;

a curved resilient load member comprising a load member surface, wherein the curved resilient load member comprises ~~with~~ a first end connected to one of the connector members and a second end connected to another one of the connector members, whereby the connection of the second end deforms the curved load member into a substantially parallel engagement with the processor and applies a constant compressive force to the processor sufficient to mate the processor with the processor socket;

a heat sink mounted on the frame member in engagement with the heat sink engagement surface and ~~adjacent to~~above the load member surface; and

the resilient load member having an opening formed therein permitting the processor to extend through the opening into contact with the heat sink, whereby the deformation of the curved resilient load member into a substantially parallel engagement with the processor results in a ~~secondary~~ non-compressive force that is ~~capable of warping the processor socket and results from the resilient load member applying the constant compressive force is~~ not transferred to the processor socket due to the coupling of the curved resilient load member to the frame member.

8. (Original) The apparatus of claim 7 wherein the frame member surrounds the processor socket.

9. (Original) The apparatus of claim 7 wherein the support member is mounted on an opposite side of the board from the frame member.

10. (Original) The apparatus of claim 7 wherein the first end of the resilient load member includes a pivotal connection and the second end includes a latched connection.

11. (Original) The apparatus of claim 7 wherein the processor includes a thermal connection surface.

12. (Canceled)

13. (Original) The apparatus of claim 11 wherein the heat sink engages the thermal connection surface.

14. (Currently Amended) An information handling system comprising:

a board member;

a support member mounted on the board member;

a processor socket mounted on the board member and coupled to a mass storage device and a system memory;

a processor seated in the processor socket;

a frame member comprising a heat sink engagement surface and mounted on the board member;

a plurality of connector members on the frame member;

a curved resilient load member comprising a load member surface, wherein the curved resilient load member comprises~~with~~ a first end connected to one of the connector members and a second end connected to another one of the connector members, whereby the connection of the second end deforms curved the load member into a substantially parallel engagement with the processor ~~and~~ such that the load member surface is located below the heat sink engagement surface and the curved resilient load member applies a constant compressive force to the processor sufficient to mate the processor with the processor socket;

a heat sink connected to the frame member ~~adjacent to~~and above the load member surface; and

the resilient load member having an opening formed therein permitting the processor to extend through the opening into contact with the heat sink, whereby the deformation of the curved resilient load member into a substantially parallel engagement with the processor results in a ~~secondary~~ non-compressive force that is ~~capable of warping the processor socket and results from the resilient load member applying the constant compressive force is~~ not transferred to the processor socket due to the coupling of the curved resilient load member to the frame.

15. (Original) The system of claim 14 wherein the frame member surrounds the processor socket.

16. (Original) The system of claim 14 wherein the support member is adjacent the frame member.

17. (Original) The system of claim 14 wherein the first end of the resilient load member includes a pivotal connection and the second end includes a latched connection.

18. (Original) The system of claim 14 wherein the processor includes a thermal connection surface.

19. (Canceled)

20. (Previously Presented) The system of claim 18 wherein the heat sink engages the thermal connection surface.

21. (Currently Amended) A method for mating a processor to a processor socket and mounting a heat sink in an information handling system comprising:

providing a board member;

mounting a support member on the board member;

mounting a processor socket on the board member;

coupling a mass storage device and a system memory to the processor socket;

providing a processor seated in the processor socket;

mounting a frame member on the board member, wherein the frame member comprises a heat sink engagement surface;

providing a plurality of connector members on the frame member;

providing a curved resilient load member comprising a load member surface, wherein the curved resilient load member comprises ~~with~~ a first end connected to one of the connector members and a second end connected to another one of the connector members, whereby the connection of the second end deforms the curved load member into a substantially parallel engagement with the processor ~~and~~ such that the load member surface is located below the heat sink engagement surface and the curved resilient load member applies a constant compressive force to the processor sufficient to mate the processor with the processor socket;

providing a heat sink connected to the frame member adjacent to the load member and in engagement with the heat sink engagement surface; and

the resilient load member having an opening formed therein permitting the processor to extend through the opening into contact with the heat sink, whereby the deformation of the curved resilient load member into a substantially parallel engagement with the processor results in a ~~secondary~~ non-compressive force that is ~~capable of warping the processor socket and results from the resilient load member applying the constant compressive force is~~ not transferred to the processor socket due to the coupling of the curved resilient load member to the frame member.

22. (Currently Amended) A heat sink mounting apparatus comprising:

a board member;

a processor socket mounted on the board member;

a processor seated in the processor socket;

a frame member comprising a heat sink engagement surface and mounted on the board member;

a plurality of connector members on the frame member;

a curved resilient load member comprising a load member surface, wherein the curved resilient load member comprises ~~with~~ a first end connected to one of the connector members and a second end connected to another one of the connector members, whereby the connection of the second end deforms the curved load member into engagement with the processor ~~and~~ such that the load member surface is located below the heat sink engagement surface and the curved resilient load member applies a constant compressive force to the processor sufficient to mate the processor with the processor socket;

a heat sink mounted on the frame member and supported by the heat sink engagement surface ~~adjacent to~~above the load member surface; and

the resilient load member having an opening formed therein permitting the processor to extend through the opening into contact with the heat sink, whereby the deformation of the curved resilient load member into a substantially parallel engagement with the processor results in a ~~secondary~~ non-compressive force that is ~~capable of warping the processor socket and results from the resilient load member applying the constant compressive force is~~ transferred to the frame member and the board member and not to the processor socket due to the coupling of the curved resilient load member to the frame member.